



1200V N-CHANNEL SILICON CARBIDE POWER MOSFET

Product Summary

BV _{DSS}	Rds(on) max	I _D T _C = +25°C		
1200V	$100 \text{m}\Omega$ @ $V_{GS} = 15V$	37.2		

Description and Applications

This SiC MOSFET is designed to minimize the on-state resistance yet maintain superior switching performance, making it ideal for highefficiency power management applications.

- Data center and telecom power supplies
- Industrial motor drives
- DC-DC converters
- Solar inverters
- EV battery chargers

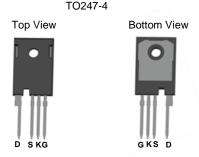
Features and Benefits

- Low On-Resistance
- High BV_{DSS} Rating for Power Application
- Low Input Capacitance
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative.

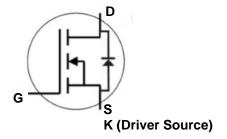
 https://www.diodes.com/quality/product-definitions/

Mechanical Data

- Package: TO247-4
- Package Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 3
- Weight: 6.6 grams (Approximate)



Pin Configuration



Internal Schematic

Ordering Information (Note 4)

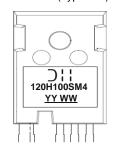
Orderable Part Number	Paakaga	Packing		
Orderable Part Number	Package	Quantity	Carrier	
DMWS120H100SM4	TO247-4 (Type WH)	30 Pieces	Tube	

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information

TO247-4 (Type WH)





Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage		V_{DSS}	1200	V
Gate-Source Voltage (dynamic)		V_{GSS}	+19/-8	V
Gate-Source Voltage (static)		V _{GSS}	+15/-4	V
Continuous Drain Current (Notes 5, 9)	$T_{C} = +25^{\circ}C$ $T_{C} = +100^{\circ}C$	I _D	37.2 23.5	А
Continuous Diode Forward Current (10µs Pulse, Duty Cycle = 1%, Note 5	Is	36	А	
Pulsed Source Current (Pulse Width t _P Limited by T _{J MAX}) (Note 5)		I _{SM}	87	A
Pulsed Drain Current (Pulse Width t _P Limited by T _{J MAX}) (Note 5)		I _{DM}	87	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Total Power Dissipation (Note 5)	T _C = +25°C	D-	208	W	
Total Fower Dissipation (Note 3)	T _C = +100°C	T _C = +100°C		VV	
Thermal Resistance, Junction to Ambient (Note 6)		$R_{\theta JA}$	25.5	°C/W	
Thermal Resistance, Junction to Case (Note 5)	R ₀ JC	0.6	C/VV		
Operating and Storage Temperature Range	T _{J,} T _{STG}	-55 to +150	°C		

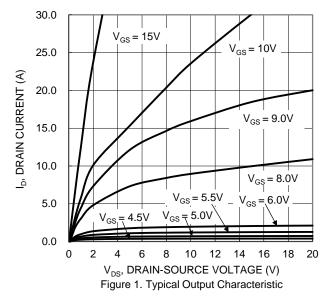
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	1200	_	_	V	$V_{GS} = 0V, I_{D} = 100\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	100	μA	V _{DS} = 1200V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_	_	±200	nA	$V_{GS} = +15/-4V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(TH)}	1.7	2.5	3.5	V	$V_{DS} = V_{GS}$, $I_D = 5mA$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	80	100	mΩ	$V_{GS} = 15V, I_D = 20A$	
Diode Forward Voltage	V_{SD}	_	4.3		V	$V_{GS} = -4V, I_{S} = 10A$	
Transconductance	gfs	_	3.8	_	S	VDS = 20V, I _D = 20A	
DYNAMIC CHARACTERISTICS (Note 7)							
Input Capacitance	C _{iss}	_	1516	_			
Output Capacitance	Coss	_	55	_	pF	$V_{GS} = 0V$, $V_{DS} = 1000V$ $V_{AC} = 25mV$, $f = 1MHz$	
Reverse Transfer Capacitance	Crss	_	4.16	_			
Coss Stored Energy	Eoss	_	35.2	_	μJ]	
Turn-On Switching Energy (Body Diode FWD)	Eon	_	538	_	μJ	$V_{GS} = -4V/+15V$, $V_{DS} = 800V$, $Rg = 0\Omega$, $I_D = 20A$, $L = 156\mu H$	
Turn-Off Switching Energy (Body Diode FWD)	Eoff	_	79	_	μυ		
Gate Resistance	R_g	_	8.26		Ω	V _{AC} = 100mV, f = 1MHz	
Total Gate Charge	Qg	_	52	_		V _{GS} = -4V/+15V, V _{DS} = 800V, I _D = 20A	
Gate-Source Charge	Q _{gs}	_	16	_	nC		
Gate-Drain Charge	Q _{gd}	_	18	_		10 – 201	
Turn-On Delay Time	t _{D(ON)}	_	10.42	_		V_{GS} = -4V/+15V, V_{DD} = 800V, Rg = 0 Ω , I_{D} = 20A, Inductive Load	
Turn-On Rise Time	t _R	_	20.67	_	no		
Turn-Off Delay Time	t _{D(OFF)}	_	15.05	_	ns		
Turn-Off Fall Time	t _F	_	5.03	_			
Body Diode Reverse Recovery Time	t _{RR}	_	9.88	_	ns		
Body Diode Reverse Recovery Charge	Q_{RR}	_	98.45	_	nC	$V_{GS} = -4V$, $V_{DS} = 800V$, $I_F = 20A$, $di/dt = 3600A/\mu s$	
Body Diode Reverse Recovery Current	I _{RRM}	_	19.94	_	Α	-1if = 20A, αί/αι = 3600A/μS	

Notes: 5. [

- 5. Device mounted on an infinite heatsink.
- 6. Device mounted on FR-4 substrate PC board, 2oz. copper, with minimum recommended pad layout.
- 7. Guaranteed by design. Not subject to production testing.
- 8. Short duration pulse test used to minimize self-heating effect.
- 9. Drain current limited by maximum junction temperature.





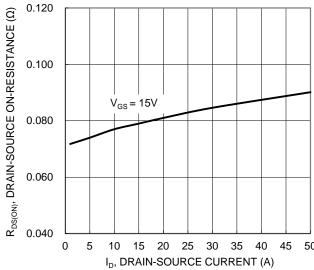


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

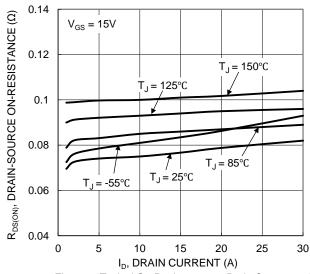


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

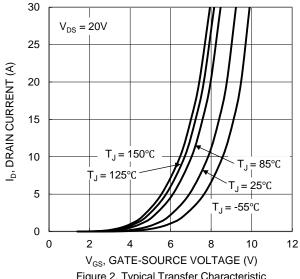
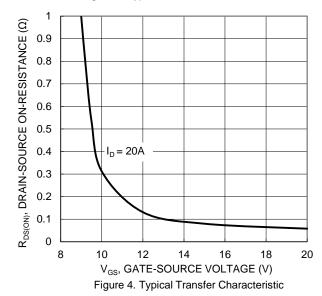


Figure 2. Typical Transfer Characteristic



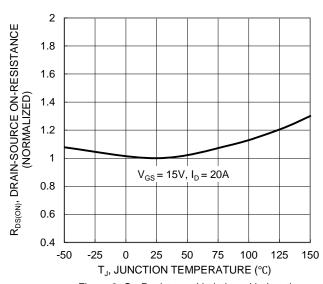


Figure 6. On-Resistance Variation with Junction Temperature





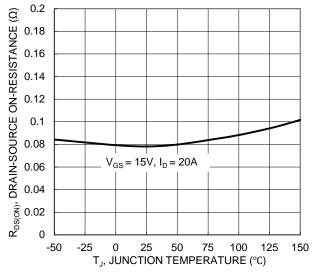
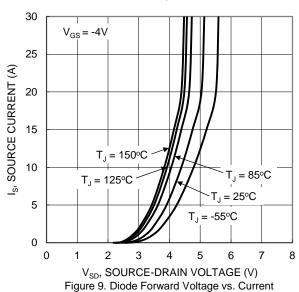
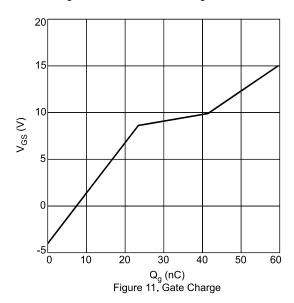


Figure 7. On-Resistance Variation with Junction Temperature





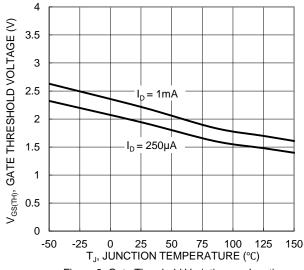
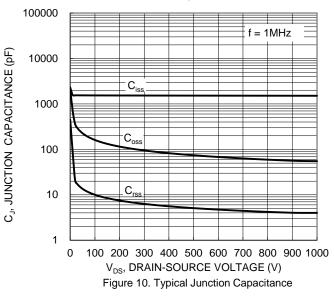
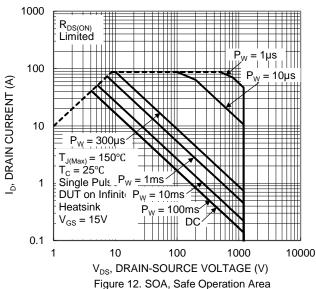


Figure 8. Gate Threshold Variation vs. Junction Temperature







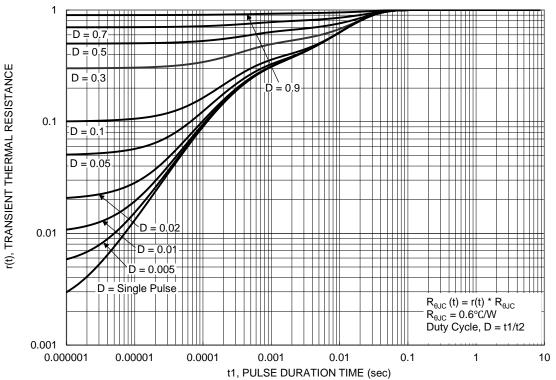


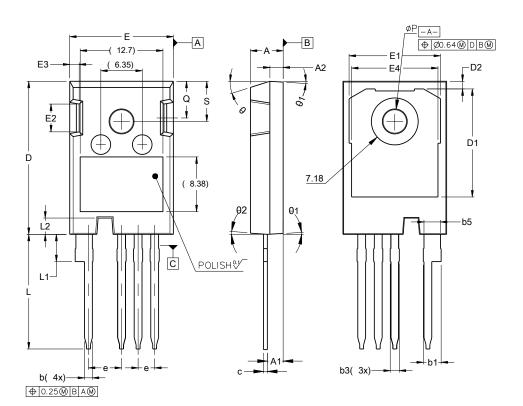
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

TO247-4 (Type WH)



TO247-4 (Type WH)				
Dim	Min	Max		
Α	4.83	5.21		
A1	2.29	2.54		
A2	1.91	2.16		
b	1.07	1.33		
b1	2.39	2.94		
b3	1.07	1.60		
b5	2.39	2.69		
С	0.55	0.68		
D	23.30	23.60		
D1	16.25	17.65		
D2	0.95	1.25		
Е	15.75	16.30		
E1	13.10	14.15		
E2	3.68	5.10		
E3	1.00	1.90		
E4	12.38	13.43		
е	2.54	BSC		
e1	5.08	BSC		
L	17.31	17.82		
L1	3.97	4.37		
L2	2.35	2.65		
ØP	3.51	3.65		
Q	5.49	6.00		
S	6.04	6.30		
θ	17.5° REF			
θ1	3.5° REF			
θ2	4° REF			
All Dimensions in mm				



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